

# Thermally conductive dispensable gap filler material

This is a highly conformable and thermally conductive silicone-free compound. It provides a thermal solution for filling large gaps with irregular surfaces at low compression force. It easily conforms and adheres to components with various shapes and sizes. No silicone means no pump-out or contamination, which is critical for the silicone-sensitive applications. It is also dispensable to enable easy adoption for automation.



## Features

- Thermal conductivity >5.0 W/m·K
- For large gaps with very low contact thermal resistance
- Easily conforming to surface irregularities with very low compression force
- Silicone-free with proven long-term reliability
- Dispensable for automation
- REACH/RoHS compliance

## Applications

- High performance CPUs
- Standard power converter and inverter
- Automotive electronics, e.g. battery
- Between any heat-generating device and heat sink/spreader

## Sample options

- Pre-filled syringe: 30cc
- Other package options available upon request

## Typical Product Properties

Test Properties		Unit	Test Method	Value
<b>Physical Properties</b>	Colour	-	Visual	Grey
	Density @25°C	g/ml	ASTM D792	2.3-2.5
	Viscosity @25°C	Pa·s	ASTM D1824 – 50/s	10-16
	Flow rate @25°C	g/min	30cc syringe with no tip attachment, 90 psi	> 80
<b>Thermal Properties</b>	Thermal conductivity	W/m·K	ASTM D5470	> 5.0
	Thermal resistance @10psi, 2.0mm thickness	K·m <sup>2</sup> /W	ASTM D5470	< 4.0x10 <sup>-4</sup>
<b>Electrical Properties</b>	Volume resistivity	Ohms·cm	ASTM D257	> 10 <sup>11</sup>
	Dielectric strength	kV/mm	ASTM D149	>5
<b>Durability</b>	High-temperature storage baking, 125°C	hrs	JESD22-A103	1000



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